THIS SHEET HAS BEEN REPLACED

REPLACEMENT SHEET
Date : 21 DEC 1995

METHOD AND APPARATUS FOR IMPROVING INTERFACIAL ADHESION BETWEEN A POLYMER AND A METAL

Abstract of the Disclosure

A leadframe (11) and a method for improving adhesion of a polymer (17, 19) to the leadframe (11). The leadframe (11) has a flag (14) having a top surface (15) and a bottom surface (18), and leads (12). Microscopic locking features (31) are formed in the top surface (15) and the bottom surface (18) of flag (14) by bombarding the flag (14) with a grit material. Thus, the top and bottom surfaces (15, 18) are roughened. A semiconductor die (13) is attached to the flag (14) by a die attach material (17) and the flag (13), the semiconductor material (13), and portions of the leads (12) are encapsulated by a molding compound. The pits improve the adhesion of the die attach material (17) and the molding compound (19) to the leadframe (11).

Figure 1

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